

App. No. 10/604,512  
Amendment dated March 30, 2006 (accompanying RCE)  
Reply to Office action of November 30, 2006

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the present application.

**Listing of Claims:**

**Claim 1 (currently amended):** A wafer holder for semiconductor manufacturing equipment, the wafer holder having a surface for carrying wafers of a predetermined diameter and comprising:

a high-frequency RF power-generating electrode circuit round in form, built into the wafer holder, the electrode circuit diameter being greater than said predetermined diameter of the wafers that the wafer holder carries, and the radial distance between the periphery of the high-frequency RF power-generating electrode circuit and the periphery of the wafer holder being greater than 2.5 mm and less than about 25 mm.

**Claim 2 (canceled)**

**Claim 3 (original):** A wafer holder as set forth in claim 1, wherein the distance between the periphery of the high-frequency RF power-generating electrode circuit built into the wafer holder and the periphery of the wafer holder is longer than the distance separating said electrode circuit from the wafer-carrying surface.

**Claim 4 (previously presented):** Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 1 is installed.

**Claim 5 (original):** Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 3 is installed.